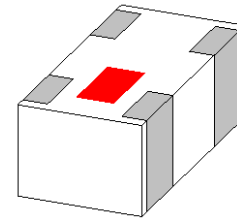


BL 1005 Series

Multilayer Chip Baluns

Features

❖ Monolithic SMD with small, low-profile and light-weight type.



Applications

❖ 2.4 ~ 2.5 GHz wireless communication systems.

Specifications

Part Number	Frequency Range (MHz)	Unbalanced Impedance (ohm)	Balance Impedance (ohm)	Insertion Loss (dB)	VSWR @BW	Phase Difference (degree)	Amplitude Difference (dB)
BL1005-05E2450_	2400 ~ 2500	50	50	1.0 max.	2.0 max.	180 ± 10	2 max.

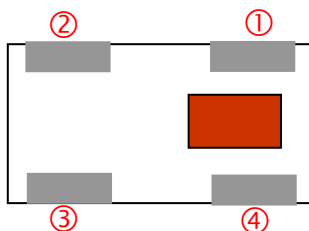
Q'ty/Reel (pcs) : 10,000
 Operating Temperature Range : -40 ~ +85 °C
 Storage Temperature Range : +5 ~ +35 °C, Humidity 45~75%RH
 Storage Period : 12 months max.
 Power Capacity : 2W max.

Part Number

BL 1005 - 05 E 2450 □ /LF
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	BL : Balun	② Dimensions (L x W)	1.0 x 0.5 mm
③ Balanced Impedance	05 : 50 ohm	④ Specification Code	E
⑤ Central Frequency	2450 : 2450MHz	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	=lead-containing /LF=lead-free		

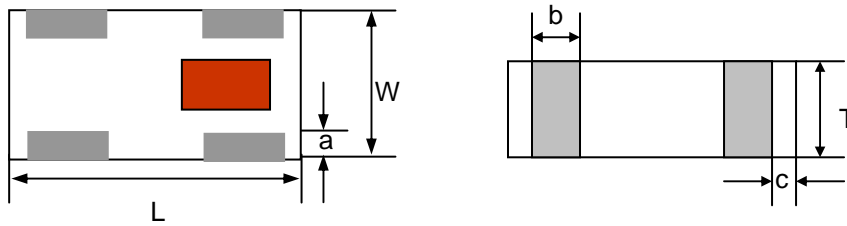
Terminal Configuration



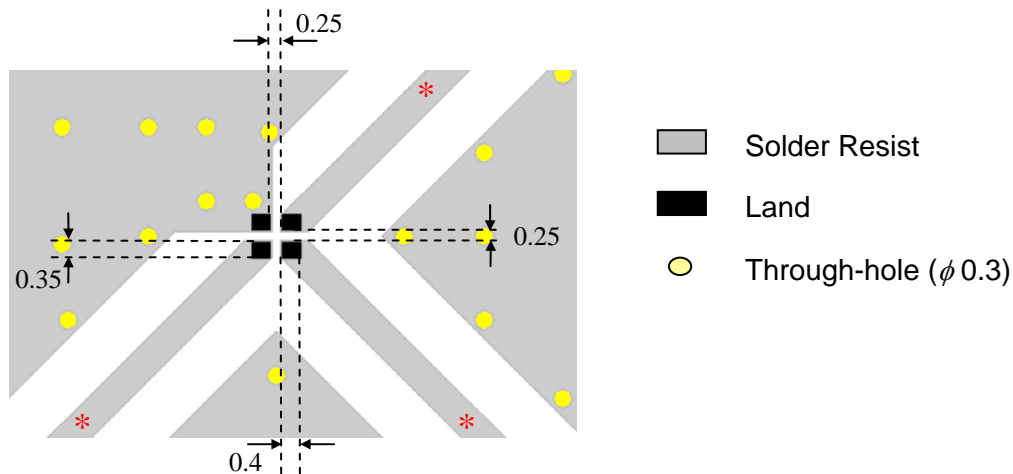
No.	Terminal Name	No.	Terminal Name
①	Unbalanced Port (IN)	③	Balanced Port (OUT2)
②	Balanced Port (OUT1)	④	GND

Dimensions and Recommended PC Board Pattern

Unit : mm

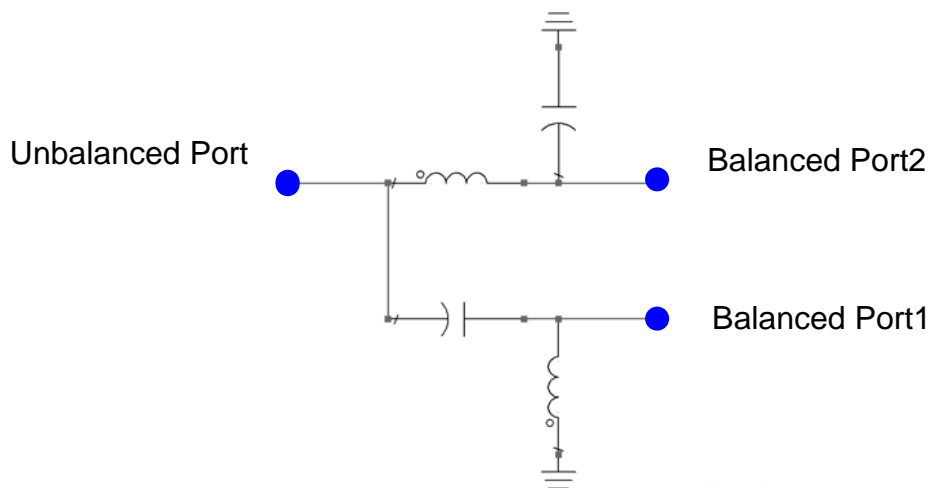


Mark	L	W	T	a	b	c
Dimensions	1.0 ± 0.1	0.5 ± 0.1	0.37 ± 0.05	0.1 +0.1/-0.05	0.25 +0.1/-0.05	0.1 +0.1/-0.05

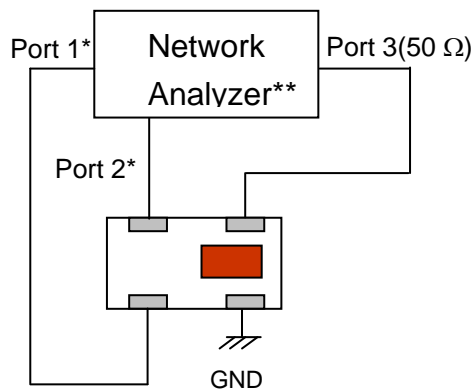


* Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

Equivalent Circuit



Measuring Diagram



Port 3: Unbalanced Port
Ports 1 and 2: Balanced Port

$$IL = S_{ds21}$$

$$RL = S_{ss11}$$

$$\text{Amp_balance} = \text{dB}(S(2,3)/S(1,3))$$

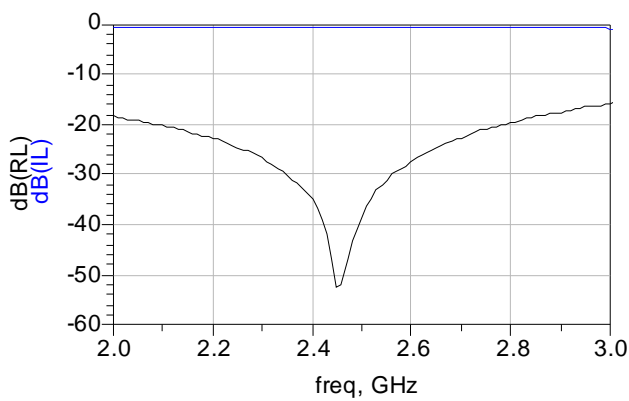
$$\text{Phase_balance} = \text{Phase}(S(2,3)/S(1,3))$$

*Impedance for ports 1 and 2 = Balanced Impedance/2

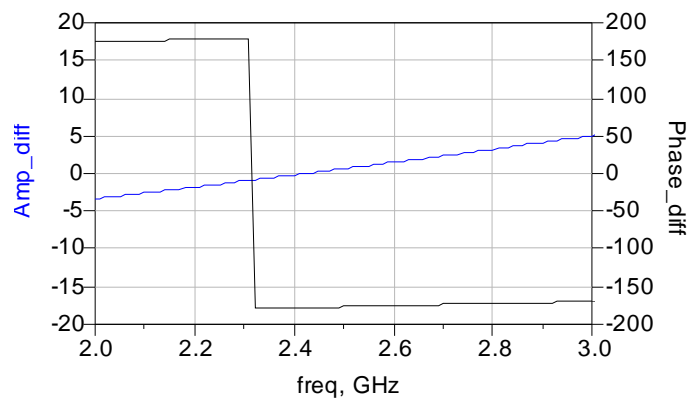
**E5071B from Agilent

Typical Electrical Characteristics (T=25°C)

Insertion and Return Loss



Amplitude and Phase Balance



Notes

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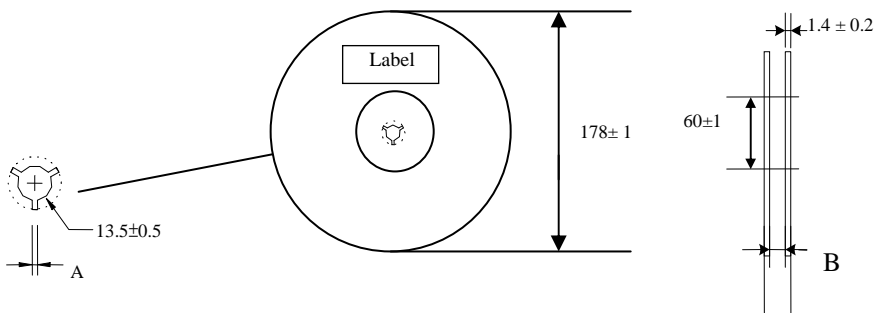
Taping Specifications

❖ Tape Dimensions (Unit: mm) & Quantity



Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
1005	2.0±	4.0±	0.62±	1.12±	2.0±	3.5±	8.0±	0.45±	10,000pcs	Paper
	0.05	0.1	0.03	0.03	0.05	0.05	0.1	0.03		

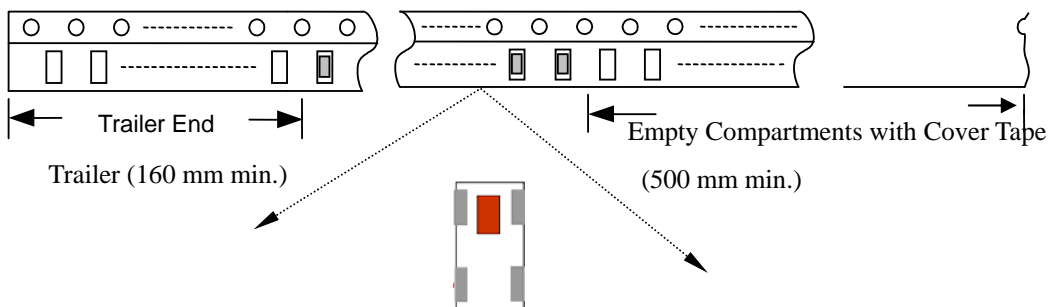
❖ Reel Dimensions (Unit: mm)



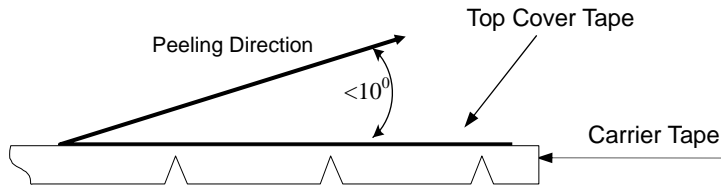
Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	A	B
1005	2.3±0.5	9.0±0.3

❖ Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

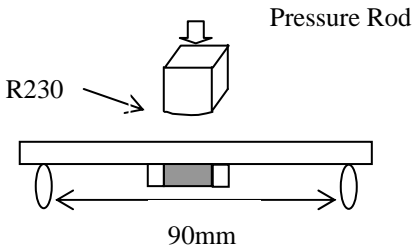
❖ **Storage Conditions**

- (1) Temperature: 15 ~35°C , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

Notes

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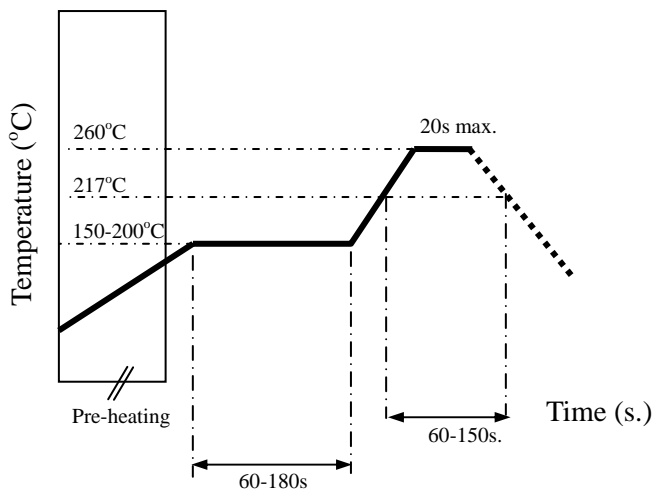
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> No apparent damage More than 95% of the terminal electrode shall be covered with new solder. 	<ol style="list-style-type: none"> Preheat: $120 \pm 5^\circ\text{C}$ Solder: $245 \pm 5^\circ\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	<ol style="list-style-type: none"> 3N minimum 	<ol style="list-style-type: none"> Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification 	<ol style="list-style-type: none"> Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. Apply a bending force of 2mm deflection 
Heat/Humidity Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $85 \pm 2^\circ\text{C}$ Humidity: 90% ~ 95% RH Duration: 1000 ± 48hrs Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> One cycle/step 1 : $125 \pm 5^\circ\text{C}$ for 30 min step 2 : $-40 \pm 5^\circ\text{C}$ for 30 min No of cycles : 100 Recovery: 1-2 hrs
Low Temperature Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $-40 \pm 5^\circ\text{C}$ Duration: 500 ± 24hrs Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



Notes

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